# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP Pro 3300 Series Microtower (MT) PC</th>
</tr>
</thead>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm motherboard, power supply and graphics card</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries on motherboard</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>The quantity may vary</td>
<td>8</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>system, processor and power supply fans</td>
<td>3</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
refractory ceramic fibers

Components, parts and materials containing radioactive substances 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel from the unit
2. Remove front bezel from the unit.
3. Remove graphic card from the PCA.
4. Remove memory from the PCA.
5. Remove all the cables from PCA
6. Remove HDD from the system
7. Remove ODD from the system,
8. Take off FIO from the unit
9. Take off CPU Cooler
10. Take off CMOS battery
11. Take off system fan
12. Take off PCA from the Unit
13. Take off PSU from the Unit
14. Remove capacitors from power supply that are greater than 2.5cm in diameter or height. The quantity may vary.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove access panel from the unit
Release the screw and slide access panel and remove it.

2. Remove front bezel from the unit.
Release 3 bezel latches from chassis by pulling outwards the bezel latches.
3. Remove graphic card from the PCA

Use screw driver to take off the screw as shown in the photo.

4. Remove memory from the PCA
5. Remove all the cables from PCA

6. Remove HDD from the system

   Rotate the screw driver to take off the HDD.
7. Remove ODD from the system.

8. Take off FIO from the unit

Rotate the screw driver to take off the FIO.
9 Take off CPU Cooler

10 Take off CMOS battery
Pull the battery holder as shown in the photo, and then the battery will off the PCA

11. Take off system fan
Rotate screw driver to loose screw and then take off the system fan.
12 Take off PCA from the Unit
Use screw driver to loose screws and then take the PCA off the Unit

13 Take off PSU from the Unit
Use screw driver to loose screws and then take the PSU off the Unit